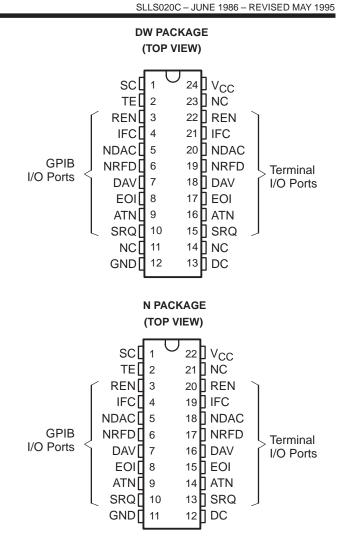
- Meets IEEE Standard 488-1978 (GPIB)
- 8-Channel Bidirectional Transceiver
- Designed to Implement Control Bus Interface
- Designed for Multicontrollers
- High-Speed Advanced Low-Power Schottky Circuitry
- Low-Power Dissipation . . . 46 mW Max per Channel
- Fast Propagation Times . . . 20 ns Max
- High-Impedance PNP Inputs
- Receiver Hysteresis . . . 650 mV Typ
- Bus-Terminating Resistors Provided on Driver Outputs
- No Loading of Bus When Device Is Powered Down (V_{CC} = 0)
- Power-Up/Power-Down Protection (Glitch Free)

description

The SN75ALS162 eight-channel general-purpose interface bus (GPIB) transceiver is a monolithic, high-speed, advanced low-power Schottky process device designed to provide the bus-management and data-transfer signals between operating units of a multiple-controller instrumentation system. When combined with the SN75ALS160 octal bus transceiver, the SN75ALS162 provides the complete 16-wire interface for the IEEE 488 bus.

The SN75ALS162 features eight driver-receiver pairs connected in a front-to-back configuration to form input/output (I/O) ports at both the bus and terminal sides. The direction of data through these driver-receiver pairs is determined by the DC, TE, and SC enable signals. The SC input allows the REN and IFC transceivers to be controlled independently.



NC-No internal connection

The driver outputs (GPIB I/O ports) feature active bus-terminating resistor circuits designed to provide a high impedance to the bus when $V_{CC} = 0$. The drivers are designed to handle loads up to 48 mA of sink current. Each receiver features pnp transistor inputs for high input impedance and hysteresis of 400 mV minimum for increased noise immunity. All receivers have 3-state outputs to present a high impedance to the terminal when disabled.

The SN75ALS162 is characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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RECEIVE/TRANSMIT FUNCTION TABLE

	CONT	ROLS		BUS-MANAGEMENT CHANNELS						DATA-TRANSFER CHANNELS		
SC	DC	TE	ATN [†]	ATN [†]	SRQ	REN	IFC	EOI	DAV	NDAC	NRFD	
				(controll	ed by DC)	(controlle	ed by SC)		(co	ontrolled by	TE)	
	Н	Н	Н	R	т			Т	т	R	R	
	Н	Н	L	K I				R	I	K	IX	
	L	L	Н	т	R			R	R	т	т	
	L	L	L	I	ĸ			Т	n.	I		
	Н	L	Х	R	Т			R	R	Т	Т	
	L	Н	Х	Т	R			Т	Т	R	R	
Н						Т	Т					
L						R	R					

H = high level, L = low level, R = receive, T = transmit, X = irrelevant

Direction of data transmission is from the terminal side to the bus side, and the direction of data receiving is from the bus side to the terminal side. Data transfer is noninverting in both directions.

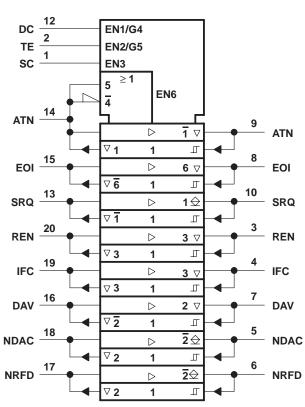
[†] ATN is a normal transceiver channel that functions additionally as an internal direction control or talk enable for EOI whenever the DC and TE inputs are in the same state. When DC and TE are in opposite states, the ATN channel functions as an independent transceiver only.

NAME	IDENTITY	CLASS			
DC	Direction Control				
TE	Talk Enable	Control			
SC	System Control				
ATN	Attention				
SRQ	Service Request				
REN	Remote Enable Bus Managemen				
IFC	Interface Clear				
EOI	End or Identify				
DAV	Data Valid				
NDAC	No Data Accepted	Data Transfer			
NRFD	Not Ready for Data				

CHANNEL IDENTIFICATION TABLE



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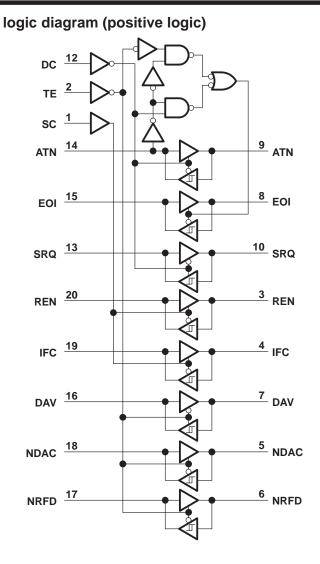


logic symbol[†]

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

▽ Designates 3-state outputs

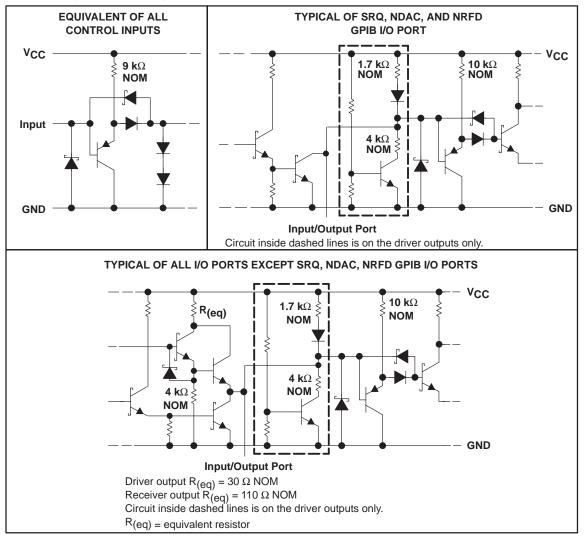
Pin numbers shown are for the N package.





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schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	
Input voltage, V _I	5.5 V
Low-level driver output current, I _{OL}	100 mA
Continuous total dissipation	. See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	– 65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network ground terminal.



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DISSIPATION RATING TABLE									
PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR	T _A = 70°C POWER RATING						
DW	1350 mW	10.8 mW/°C	864 mW						
N	1700 mW	13.6 mW/°C	1088 mW						

recommended operating conditions

			MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V	
High-level input voltage, VIH	2			V		
Low level input voltage, VIL					0.8	V
High level output ourrest low	Bus ports with 3-state outputs			- 5.2	mA	
High-level output current, IOH	Terminal ports				- 800	μΑ
	Bus ports				48	A
Low-level output current, IOL	Terminal ports				16	mA
Operating free-air temperature, T _A	0		70	°C		

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST	MIN	TYP†	MAX	UNIT		
VIK	Input clamp voltage		lj = -18 mA	IJ = -18 mA			-1.5	V	
V _{hys}	Hysteresis voltage (V _{IT+} – V _{IT} _)	Bus			0.4	0.65		V	
VOH‡	High-level output voltage	Terminal	I _{OH} = -800 μA	I _{OH} = -800 μA				V	
VOH+	High-level output voltage	Bus	$I_{OH} = -5.2 \text{ mA}$		2.5	3.3		v	
Va		Terminal	IOL = 16 mA			0.3	0.5	V	
VOL	Low-level output voltage	Bus	I _{OL} = 48 mA			0.35	0.5	V	
lį	Input current at maximum input voltage	Terminal	VI = 5.5 V		0.2	100	μΑ		
IIН	High-level input current	Terminal and	VI = 2.7 V		0.1	20	μA		
۱ _{IL}	Low-level input current	control inputs	VI = 0.5 V		-10	-100	μA		
N	Voltage at bus port		Driver disabled	$I_{I(bus)} = 0$	2.5	3.0	3.7 V		
VI/O(bus)	vollage at bus port		Driver disabled	$I_{I(bus)} = -12 \text{ mA}$			-1.5	v	
			on Driver disabled	$V_{I(bus)} = -1.5 \text{ V to } 0.4 \text{ V}$	-1.3				
				$V_{I(bus)} = 0.4 \text{ V to } 2.5 \text{ V}$	0		- 3.2	2	
II/O(bus)	Current into bus port	Power on		$V_{I(bus)}$ = 2.5 V to 3.7 V			+ 2.5 - 3.2 mA		
<i>(, C</i> (, , , , , , , , , , , , , , , , , , ,				V _{I(bus)} = 3.7 V to 5 V	0		2.5		
				V _{I(bus)} = 5 V to 5.5 V	0.7		2.5		
		Power off	V _{CC} = 0,	V _{I(bus)} = 0 to 2.5 V			- 40	μΑ	
1	Short-circuit output	Terminal			-15	- 35	-75		
los	current	Bus			- 25	- 50	-125	mA	
ICC	Supply current		No load,	TE, DC, and SC low		55	75	mA	
C _{I/O(bus)}	Bus-port capacitance		$V_{CC} = 0$ to 5 V,	$V_{I/O} = 0$ to 2 V, f = 1 MHz		30		pF	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. [‡] V_{OH} applies to 3-state outputs only.



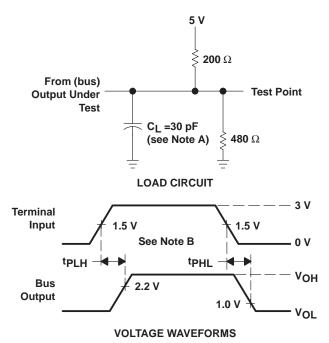
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switching characteristics over recommended range of operating free-air temperature, V_{CC} = 5 V

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN TYP [†]	МАХ	UNIT	
^t PLH	Propagation delay time, low- to high-level output	Terminal	Due	C _L = 30 pF,	10	20		
^t PHL	Propagation delay time, high- to low-level output	Terminal	Bus	See Figure 1	12	20	ns	
^t PLH	Propagation delay time, low- to high-level output	Due	Tomainal	C _I = 30 pF,	5	10		
^t PHL	Propagation delay time, high- to low-level output	Bus	Terminal	See Figure 2	7	14	ns I	
^t PZH	Output enable time to high level		Bus (ATN, EOI, REN, IFC,			30	0 ns	
^t PHZ	Output disable time from high level			C _L = 15 pF,		20		
t _{PZL}	Output enable time to low level	TE, DC, or SC		See Figure 3		45		
^t PLZ	Output disable time from low level		and DAV)			20		
^t PZH	Output enable time to high level					30		
^t PHZ	Output disable time from high level		Torminal	C _L = 15 pF,		25		
t _{PZL}	Output enable time to low level	TE, DC, or SC	Terminal	See Figure 4		30	ns	
t _{PLZ}	Output disable time from low level	1				25		
- ^ 11 4	ical values are at $T_{A} = 25^{\circ}C$	-	8					

[†] All typical values are at $T_A = 25^{\circ}C$.

PARAMETER MEASUREMENT INFORMATION

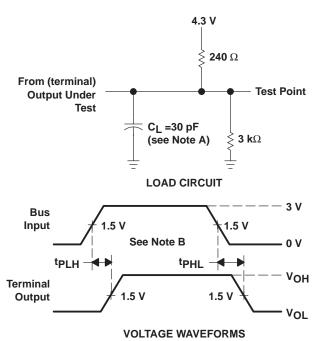


- NOTES: A. CL includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .





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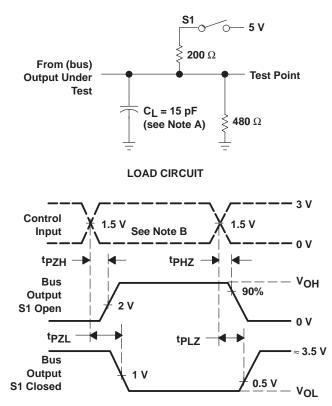
PARAMETER MEASUREMENT INFORMATION

- NOTES: A. C_L includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_r \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .





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PARAMETER MEASUREMENT INFORMATION

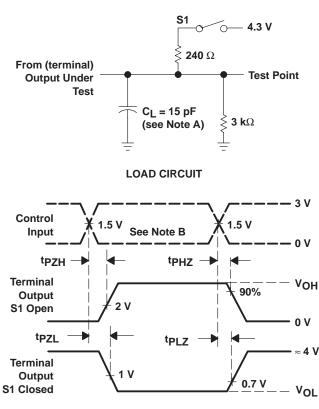
VOLTAGE WAVEFORMS

- NOTES: A. CL includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

Figure 3. Bus Load Circuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION

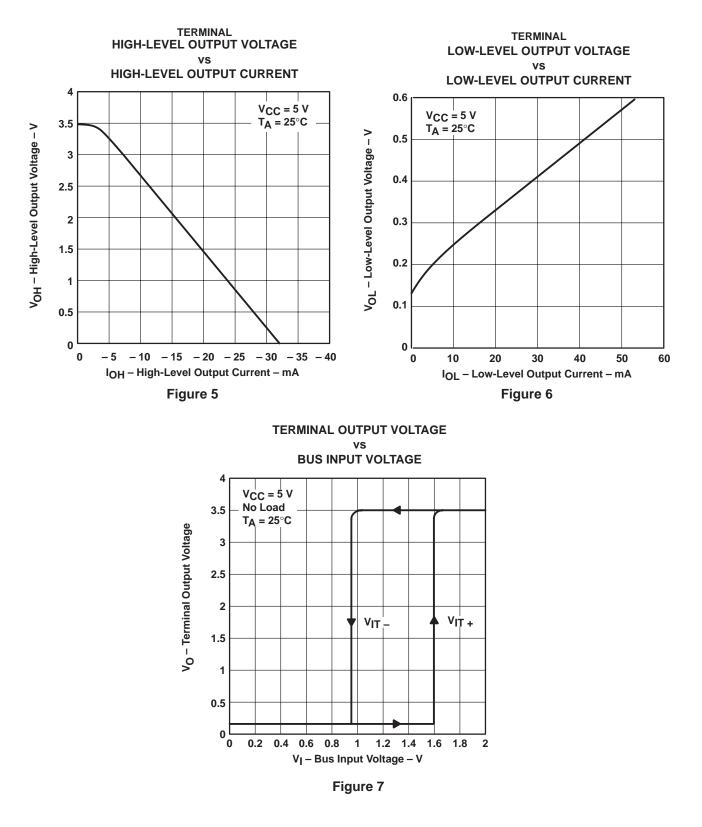
VOLTAGE WAVEFORMS

- NOTES: A. CL includes probe and jig capacitance.
 - B. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .

Figure 4. Terminal Load Circuit and Voltage Waveforms



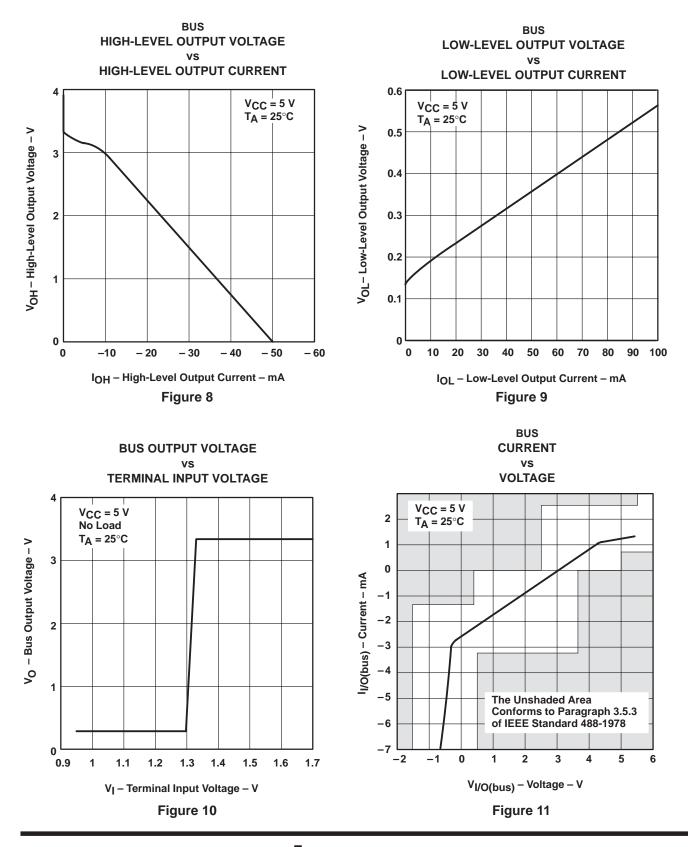
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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS





PACKAGING INFORMATION

Orderable Device	Status	Package Type	•		Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
SN75ALS162DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS162	Samples
SN75ALS162DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS162	Samples
SN75ALS162DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS162	Samples
SN75ALS162DWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS162	Samples
SN75ALS162DWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS162	Samples
SN75ALS162DWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS162	Samples
SN75ALS162N	OBSOLETE	PDIP	Ν	22		TBD	Call TI	Call TI	0 to 70		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.



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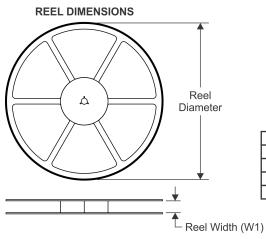
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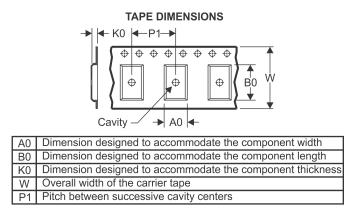
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS162DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

5-Feb-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS162DWR	SOIC	DW	24	2000	367.0	367.0	45.0

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



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